BGA Heat Sink - High Performance Device Specific - Freescale





ATS Part#:

Description:



ion: 21.00 x 45.00 x 9.00 mm BGA Heat Sink - High Performance Device Specific -Freescale

 Heat Sink Type:
 Freescale

 Heat Sink Attachment:
 maxiGRIP

 Equivalent Part Number:
 ATS-59000-C2-R0 Discontinued

*Image above is for illustration purpose only.

Features & Benefits

- Designed for flip-chip processors such as Freescale MPCs
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- · Comes preassembled with high performance, phase changing, thermal interface material

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	6.1 °C/W	5 °C/W	4.4 °C/W	3.9 °C/W	3.6 °C/W	3.4 °C/W	3.3 °C/W
	Ducted Flow	4.2	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	21.00 mm	45.00 mm	9.00 mm	59 mm	T766	BLACK-ANODIZED
e e e e e e e e e e e e e e e e e e e	 Dimension ATS-5900 (Saint Gol Thermal p application ATS resen performar ATS certif Optional r 	00-C2-R0 is the example bain C1100F). NOT performance data ar n. rves the right to upd nce. ies that this heat sir maxiGRIP™ Installa	omponent size. height from the botto ct heat sink assembl E: Saint Gobain C11 e provided for refere ate or change its pro- ak assembly is RoHS tion/Removal Tool S ustom options availa	ly with an equivalent 00F is discontinued ence only. Actual per oducts without notice S-6 and REACH cor Set P/N: MGT170	t thermal effective rformance	interface material 12/31/10. e may vary by

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), **sales@qats.com** or **www.qats.com**.



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